

## UM11219 Ringo TEA2016 development software with GUI Rev. 1.05 — 30 July 2019

**User manual** 

#### **Document information**

Information	Content
Keywords	TEA2016, LLC, PFC, controller, I2C, USB, parameters, programming, MTP, GUI, Ringo, software, interface
Abstract	The Ringo TEA2016 development software with GUI is a development tool that enables working with the TEA2016 settings using a computer and the TEA2016DB1514 USB I2C interface board. The software and interface are intended for engineering work in a lab environment as part of power supply development.



## **Revision history**

Revision history								
Rev	Date	Description						
v.1	20190730	Initial version						

### **1** Introduction

The TEA2016 development software Ringo GUI user manual shows how the GUI is set up and what functions it provides.

The working of parameter settings, as part of designing a power supply with the TEA2016, is discussed in the TEA2016 data sheet (Ref. 1) and the application note (Ref. 2). The info buttons in the GUI also provide information on the working of the parameter in a pop-up window.

**Note:** Some screenshots of the Ringo GUI may deviate from the version that you are currently using. The reason is that the tool is regularly updated during its development. This document is based on the Ringo v1.25 (February 2019) status.

### 1.1 Software license agreement

When starting up the Ringo software, the license agreement, which appears on the screen as a pop-up window, must be accepted.

#### 1.2 Different appearance

Because the Ringo GUI uses functions of the operating system, some (personal) settings in the operating system can influence colors and character appearances. The screenshots in this document may be different from the screens on the computer of the user.

### 1.3 Fixed window pixel size GUI window.

To avoid issues on showing all functions in an orderly manner, the Ringo GUI uses a fixed pixel size window.

When the GUI is shown on a display (automatically) set on a low resolution, the GUI window may not fit completely on the display. In this case, to show the complete window, the resolution of the display (enforce a higher resolution) or the computer (select a resolution the display can handle) must be adapted.

The pop-up windows are not fixed and scalable.

#### 1.4 64-bit and 32-bit versions

The Ringo software is available in two versions:

- For a 64-bit operating system
- For a 32-bit operating system

UM11219

Ringo TEA2016 development software with GUI

## 2 Setup and functions of Ringo

### 2.1 Chapters and tabs

The parameters and settings are organized in related sections.

Clicking three large blue buttons gives the option to select three chapters.

Each chapter includes tabs.

#### General

- Configuration
- Miscellaneous
- Info Sheet

#### PFC

- Operation
- Protection

#### LLC

- Operation
- Protection
- Power Good



#### Ringo TEA2016 development software with GUI

Each tab shows parameters and settings. They are grouped in blocks with similar functions.

For example, Figure 1 shows the LLC operation tab that contains four blocks:

- Low Power Mode
- Startup
- Feedback
- Burst Mode

#### 2.2 Selecting a parameter value

Clicking the drop-down button, selects a parameter for modification.

Default value shown in standard font Other values shown in italic font	Click to open the drop-down table Click info button to open a window with information on this parameter LP number of peaks drop-down table	
Figure 2. Example of pa	arameter elements	aaa-033805



### 2.3 Adding modification restrictions

To block modification of one or more parameters. a separate program can be used.

Dragging and dropping the .prf file into the left side of the Ringo GUI activates it. The blocked parameters are greyed out and only show the values.

The ParamEdit.exe tool is included in the Ringo software package. Initially, all parameters are marked with a "v". Removing the mark by clicking it, blocks this parameter after the saved .prf file is activated.

Ringo TEA2016 development software with GUI

File IO View Help												2	Sear
TEA2010	5												
0 10 30 BM LP			HP	0	pp1 24	Op 14	p2 10	155	6			P	out (%
Operation Protection Power	Good				[	Re	eset				Prote	ection	n stat
Low Power Mode				Feedback									
HP-LP Transition level	30%	•	0		Opto c	oupl	er currer	ntlev	el 8	DuA		٠	0
LP-BM Transition level	10%	•	0										
LP number of peaks	2	-	0	Burst Mode									~
dVcap offset	0mV	Ŧ	0			E	3M Freq	luenc	y 8	OOHz		•	
Zero Power Slope	6mV/us	Ŧ	0	BM	Energy	per C	ycle Inc	reas	e 1			*	0
Vdump level	2.6V	Ŧ	0			BM-	LP Hyst	eresi	s 5	0%		Ŧ	0
HP-LP Hysteresis	20%	-	0		Minin	num	cycles i	n bur	st 3			•	0
				E	Burston	end b	y opto o	curre	nt 2	5		•	0
Startup	7~					LP-	BM dela	ay tim	e 0	S		Ŧ	0
LLO and the second	74				BM	ILP	ysteres	is filte	er 4			٣	0
LLC softstart speed		-							-				
LLC softstart speed Maximum (startup) frequency	35UKHZ		~	0.1							4		
LLC softstart speed Maximum (startup) frequency LLC softstart current limit	0.75V	•	0	Cycles	1		132		84		36		
LLC softstart speed Maximum (startup) frequency LLC softstart current limit SNSBOOST compensation	350KHZ 0.75V -1.4	•	0	Cycles Start	1 180	•	132	•	84	•	36	•	0

Figure 4. Several parameters can be restricted for modification (only showing the actual value in greyed out style) using a separate tool ParamEdit.exe

Ringo TEA2016 development software with GUI



UM11219 User manual

### Ringo TEA2016 development software with GUI

Development				<ul> <li>info</li> <li>TeaConnect.dll</li> <li>Tea2016_fields.dl</li> <li>tea2016_com.dll</li> <li>TEA2016.dll</li> <li>tea myc.dll</li> </ul>							
File IO View Help				Selection1.prf			_	_		21	Searc
The to their help				Ringo.exe							Jeare
TEA2010	2			<ul> <li>ParamEdit.exe</li> <li>IibMPSSE-I2C.dll</li> </ul>							
Operation Protection Power	Good	roj	<b>)</b>	Opp1 124	0 1 R	pp2 40 eset	155		Prote	Po	out (%) i statur
Low Power Mode				Feedback							
HP-LP Transition level	30%		0	Opt	o coup	ler current	level	80uA		•	0
LP-BM Transition level	10%		0								
LD sumbas of soulis	2			Burst Mode							
		_				BM Freque	ency	800H	z	•	0
	0-1/						9969	1		-	0
dVcap offset	0mV	·		BM Ener	gy per	Cycle Incre					
dVcap offset Zero Power Slope	0mV 6mV/us	*	0	BM Ener	gy per BM	Cycle Incre	resis	50%		*	0
dVcap offset Zero Power Slope Vdump level	0mV 6mV/us 2.6V	v v	0	BM Ener	gy per BM	Cycle Incre -LP Hyster	resis	50%		~ •	0
dVcap offset Zero Power Stope Vdump level HP-LP Hysteresis	0mV 6mV/us 2.6V 20%	* * *	0	BM Ener	gy per BM inimum	Cycle Incre -LP Hyster cycles in I	resis burst	50%		•	0
dVcap offset Zero Power Slope Vdump level HP-LP Hysteresis	0mV 6mV/us 2.6V 20%	* * *	0	BM Ener M Burste	gy per BM inimum on end	Cycle Incre -LP Hyster cycles in I by opto cu	resis burst rrent	50% 3 2.5		•	0
dVcap offset Zero Power Slope Vdump level HP-LP Hysteresis Startup	0mV 6mV/us 2.6V 20%	· ·	0 0 0	BM Ener M Burste	gy per BM inimum on end LP	Cycle Incre -LP Hyster cycles in I by opto cu -BM delay	resis burst rrent time	50% 3 2.5 0s		•	0 0 0
dVcap offset Zero Power Stope Vdump level HP-LP Hysteresis Startup LLC softstart speed Maximum (startur) fearware	0mV 6mV/us 2.6V 20% 7x 350kHz	· · · · · · · · · · · · · · · · · · ·	0 0 0	BM Ener M Burste	gyper BM inimum on end LP BM LP	Cycle Incre -LP Hyster cycles in I by opto cu BM delay hysteresis	resis burst rrent time filter	50% 3 2.5 0s 4		•	0 0 0 0
dVcap offset Zero Power Stope Vdump level HP-LP Hysteresis Startup LLC softstart speed Maximum (startup) frequency	0mV 6mV/us 2.6V 20% 7x 350kHz 0.75V		0 0 0 0	BM Ener M Burste	gyper BM inimum on end LP BM LP	Cycle Incre -LP Hyster cycles in I by opto cu BM delay hysteresis	resis burst rrent time filter	50% 3 2.5 0s 4		· ·	0 0 0
dVcap offset Zero Power Stope Vdump level HP-LP Hysteresis Startup LLC softstart speed Maximum (startup) frequency LLC softstart current limit	0mV 6mV/us 2.6V 20% 7x 350kHz 0.75V	•	0 0 0 0	BM Ener M Burst Cycles	gyper BM inimum on end LP BM LP 1	Cycle Incre -LP Hyster cycles in I by opto cu -BM delay hysteresis 2 132	resis burst rrent time filter	50% 3 2.5 0s 4	4	· · · · ·	0 0 0 0
dVcap offset Zero Power Stope Vdump level HP-LP Hysteresis Startup LLC softstart speed Maximum (startup) frequency LLC softstart current limit SNSBOOST compensation	0mV 6mV/us 2.6V 20% 7x 350kHz 0.75V -1.4	•	0 0 0 0	BM Ener M Burste Cycles Start 186	gyper BM inimum on end LP BM LP 1 1	Cycle Incre -LP Hyster cycles in I by opto cu BM delay hysteresis 2 132	resis burst time filter 8	50% 3 2.5 0s 4	4	· · · · · · · · · · · · · · · · · · ·	0 0 0 0
dVcap offset Zero Power Stope Vdump level HP-LP Hysteresis Startup LLC softstart speed Maximum (startup) frequency LLC softstart current limit SNSBOOST compensation	0mV 6mV/us 2.6V 20% 7x 350kHz 0.75V -1.4	· · ·	0 0 0 0 0	BM Ener M Burst Cycles Start 180 Stop 36	gyper BM inimum on end LP BM LP 1 0 •	Cycle Incre -LP Hyster cycles in I by opto cu BM delay hysteresis 2 132 · 84 ·	resis burst time filter • 8-	50% 3 2.5 0s 4 3 4	4 36 180	· · ·	0 0 0 0
dVcap offset Zero Power Stope Vdump level HP-LP Hysteresis Startup LLC softstart speed Maximum (startup) frequency LLC softstart current limit SNSBOOST compensation	0mV 6mV/us 2.6V 20% 7x 350kHz 0.75V -1.4	•	0 0 0 0	BM Ener M Burst Cycles Start 180 Stop 36	gyper BM inimum on end LP BM LP 1 0 •	Cycle Incre -LP Hyster cycles in I by opto cu -BM delay hysteresis 2 132 	resis burst rrent time filter • & • 1:	50% 3 2.5 0s 4 3 4	4 36 180	· · · · · · · · · · · · · · · · · · ·	0 0 0 0

Figure 6. Dragging and dropping the .prf file into the left side of the Ringo GUI activates it. The parameters blocked for modification are greyed out and only show the value

### 3 Information

### 3.1 Protection registers and LEDs

The reset button clears all protections.

Protections that are triggered are stored in the MTP and shown in the GUI by an LED turning from green to orange. Selecting the LED using the mouse shows the protection name. When the LED is orange, clicking provides extra information.

Protection status Reset Advanced S aaa-033811 Figure 7. Protection LEDs



At start-up, the status of the protection registers is read. These registers are constantly updated during operation.

If a protection is triggered, it is stored in the MTP unless it was already set earlier. It avoids that MTP writes when it is not necessary.

#### Table 1. Protections registers shown in the GUI

	Protections
1	PFC overcurrent protection
2	PFC overvoltage protection (DRAINPFC)
3	PFC overvoltage protection (SNSBOOST)
4	LLC OPP1
5	LLC OPP2
6	LLC maximum start-up time exceeded
7	LLC overcurrent protection

UM11219 User manual

Ringo TEA2016 development software with GUI

	Protections
8	LLC overvoltage protection
9	External overtemperature protection
10	Internal overtemperature protection
11	Fast disable
12	LLC maximum on-time exceeded
13	LLC maximum optocoupler current in burst
14	LLC capacitive mode
15	MTP read failure
16	OPP via SUPIC UVP

If the IC is not locked, the protection registers can be reset using the GUI (RESET button). After resetting, the LEDs becomes orange again when the protection is triggered.

If a protection is triggered and showing an orange LED, that does not always mean that the system has stopped operation (and restarted). A timing filter may prevent that the system stops. Or the protection does not lead to stopping but to just limiting a condition. The triggering indicates that this function may be critical and attention is necessary.

### 3.2 Info buttons

Settings and protection LEDs provide extra information. When clicking the info button, a window with information pops up. The window can be scrolled through and its size can be adjusted. Opening multiple windows at the same time is also possible.

#### Ringo TEA2016 development software with GUI



### 3.3 Mode transitions and protection levels on a power scale

0 10 BM LP	30	HP	Opp1 124	Opp2 140	155	Pout (%)			
< Normal e	operating power range	Pout, nominal	(=100%)			aaa-033817			
Figure 10. M	igure 10. Mode transitions and protection levels on a power scale								

Mode transitions levels between the operating modes HP, LP, and BM can be set independently using parameters. Also, protection levels related to output power can be set. These levels are always shown as a reference for parameter design choices that were made.

### 3.4 Warnings

When a combination of settings is chosen that may be conflicting or runs the risk of creating a problem, a warning is provided to check if the choice is correct. When clicking the general warning box, a pop-up window shows which parameters can be checked.

Ringo TEA2016 development software with GUI

			Opp1 Opp2
BM	HP		124 140 155 Pout (%)
Low Power Mode	•		BM-LP-HP mode transitions overlap and may conflict. Jump to "LP-BM Transition level"
ow Power Mode HP-LP Transition level 14%	-	0	BM-LP-HP mode transitions overlap and may conflict. Jump to "LP-BM Transition level"
LP-BM Transition level 20%	•	0	Hide and don't show ain
LP number of peaks 2	-	0	

The warning system is a help function for the user and does not provide a full coverage of all possible conflicts.

There is no limit to combinations. The user has full freedom of choice.

### 3.5 Search function

Ringo includes a search function to find the location of a setting or related settings.

The search function can be activated:

- View menu: select search
- Ctrl+F
- · Click the search field in top right corner



By clicking one of the search results, the view shows the correct tab and highlights the parameter.

### 4 Writing and reading settings (IO)

### 4.1 W and R button

When one or more new parameter values are selected, pushing the Write button activates them. The Write button writes the changed fields to the TEA2016.

To check if the changes were successful, a write action is automatically followed by a read action. If successful, the blue text color of the changed field changes to black.



The read button can be used for reading (all) device settings. Reading the device settings can be used for double checking or to compare the difference between a loaded .mif file with the actual IC settings.

The Read and Write button functions can also be activated in the IO menu or by pressing F5 and F6.

The IO menu also includes the option to write all parameters instead of only the changed parameters (F7). Only use this option to double check because how many times the MTP fields can be written is limited (guaranteed 200x, in practice 700 times).



### 4.2 Read lock and write lock

After programming, the MTP can be locked for reading and writing settings.

Only a reset to factory defaults, can unlock the IC. After the reset, the IC can be programmed again.

#### Ringo TEA2016 development software with GUI

			Please co	nfirm
IO P	View Help Read Write Write all Read all on connect	F5 F6 F7	0	Once the read-lock is applied, the settings of the device can no longer be read. Only a 'Reset to factory defaults' will remove the read-lock, but all settings will be lost and restored to their default values. Click OK to apply the read-lock
1	Reset to factory defa Apply read-lock Apply write-lock	ults	Please cor	OK Cancel
			•	Once the write-lock is applied, the settings of the device can no longer be changed. Only a 'Reset to factory defaults' will remove the write-lock, but all settings will be lost and restored to their default values. Click OK to apply the write-lock
				OK Cancel
jure 1	5. Read lock and	l write lock		aaa-033829

If there are problems, the protection registers and the vendor code (identifier number for a specific product) can still be read for analyses after read lock and write lock.

### 4.3 Reset to factory defaults

This function restores all default values in the MTP (see Section 5.1.2).

### 4.4 Info sheet

The info sheet tab contains information about the IC (MTP) status.

The sheet shows that the testing and calibration was completed in the NXP Semiconductors production. It also shows if the settings can be read and/or changed. It reflects the status of the read lock and write lock setting.

The Ringo program calculates a CRC value from the settings, which is then displayed. The value is calculated from the actual values in the Ringo (values displayed onscreen). By reading the MTP content of an IC, the CRC number can be used to check ICs on correct MTP content or for identification of a product version.

The vendor code is a section (MTP page 31, 16 bits) that can be used for identification of the IC (programming) version. The vendor code remains readable also after read lock.

Ringo TEA2016 development software with GUI

* Ringo - TEA2016 Deve	lopment File IO View He	lp				P Search	
Õ	0 10 30 BM LP		HP	Opp1 ( 124	Opp2 140	155 Pout (%)	
	Configuration Misc	ellaneous Info shee	t		Reset	Protection status	Read and write locked
11	V C	alibration is device is calibrated durin	g the final test.	ſ	/	Calibration This device is calibrated during the final	test.
-	V R Th No	eadability is device is readable. te: Applying the read-lock is	a permanent action.	4	•	Readability This device is locked and its memory co The vendor-code and the protection reg	annot be read. ister are always readable.
	V N	<b>'ritability</b> is device is writable. te: Applying the write-lock is	a permanent action.	Å	•	Writability This device is locked and its memory c	annot be written.
	V Ve	endor code 0x0001 ndor specific code as cross	1 reference for the progra	mmed settings.		Vendor code 0x0001 Vendor specific code as cross referenc	() e for the programmed settings.
	CF	RC code 0xDF9 IC code from pages 30 to 7.	D 😗	4	•	CRC code 0xDF9D This device is locked for reading and th	e CRC code cannot be calculated from MTP memory
	🖋 FT232H (SN: FT1WRI)	/A). UM232H	NXP co	nfidential		IIII 0 <mark>N/</mark> P	
ure 16. Inf	o sheet						aaa-033830

### 4.5 Connection

The connection is constantly checked by reading the protection status and updating the LEDs (poll protection register).

The status of communication is shown.

No connection 🛦		🖋 FT232H (SN: FT103NFF). UM232H 🗼		🖉 FT232H (SN: FT103NFF). UM232H					
No communication	Communication with	USB I2C interface = OK	Communication with	USB I2C interface = OK					
	Communication with	TEA2016 = Not OK	Communication with	TEA2016 = OK					
				aaa-033831					
Figure 17. Connection status									

### 4.6 Connection quality

The Ringo GUI is often used with a development version of the controller IC. While the power supply is operation, all  $I^2C$  communication is running via pin 7 and pin 12. Changes can be made on the fly.

In this situation, there is a risk of disturbances on the  $I^2C$  bus because of the converter switching high dV/dt signals (like HB and DRAINPFC) are causing spikes on the SDA and SCL connection. It can disturb communication. When the disturbances are extreme, ICs connected to the  $I^2C$  bus can be damaged.

The connection quality indicator at the bottom of the Ringo GUI screen helps to detect when something is going wrong.

Normally, the indicator provides four green bars. At this level, there may be an occasional error that the system can correct.

#### Ringo TEA2016 development software with GUI

When the indicator shows three yellow bars, communication is showing errors often. Moving the I<sup>2</sup>C connection cable to a better position may provide good quality again.

When the indicator shows two orange bars or one red bar, the situation is bad and changes are required.

The info button pop-up provides detailed information about what can be done to improve the connection quality. It also provides a method to avoid errors completely.



### 5 TEA2016 MTP and registers

### 5.1 MTP memory and registers

The MPT in the IC is a permanent (but changeable) memory like a flash memory. When the IC supply voltage goes down, the content remains.

The registers in the IC are a temporary memory. When the supply voltage goes down, the content is lost.



### 5.1.1 IC operation

For correct operation, the stored MTP setting values are copied to the registers of the IC at start-up.

The IC operation works with the register values. It can only store the protection registers in the MTP memory. The user or a programming unit must store or modify the remaining MTP content when necessary.

### 5.1.2 Default settings

When erasing the MTP (set all values to zero), the settings are at default. The default values show a predefined "middle of the road" type of operation. Most applications run well on default values, but not optimal. In some cases, the default settings conflict with the values of the converter and external component values. The result can be unintended protection triggering.

The "Reset to factory defaults" function in the Ringo GUI can restore the default settings.

Ringo TEA2016 development software with GUI

IC	View Help Read	F5				
	Write	F6				
	Write all	F7				
1	Read all on connect					
1	Reset to factory defa	ults				
	Apply read-lock	7		HP		
	Apply write-I Reset t	he MTP m	emory to	factory d	lefault value	es
					aaa-03	3834
re 20. Reset t	o factorv defaults fu	nction				

### 5.1.3 Saving and loading setting by .mif file

The user can read and write the MTP and the registers via  $I^2C$ . A TEA2016-specific  $I^2C$ -based protocol is required for this action.

Settings can be changed individually. A complete collection of settings can be saved on the computer as a .mif file. A saved .mif file can be used to program the MTP of an IC by opening it in the GUI and writing it in the IC.

If the .mif file must contain the IC settings or MTP settings, first read the content again to be sure.

You can use the .mif file to share the settings with other engineers.

When loading settings from a .mif file, they are displayed on the screen for review. The settings must be written to modify the IC settings.



Ringo TEA2016 development software with GUI

🔁 💭 🗢 🔳 Desktop 🔸	✓ ✓ Search Desktop
File name: Test	•
Save as type: MIF (*.mif)	•
Browse Folders	Save Cancel
	4

### 5.1.4 List of settings

All the settings shown on the GUI screen can be copied and pasted in another computer program.

Make sure that the GUI screen contains the content that you want to copy. If it must show the IC settings or MTP settings, first read the content again to be sure.



### 5.1.5 Double check changed settings

The change handling of Ringo is made to provide reliable register and MTP modification and clear representation on the GUI screen. In some situations, it may still be unclear to the user if changes were indeed activated or stored.

To double check, the TEA2016 can be stopped (disconnect the mains voltage) and started again to refresh the settings. At start-up, the IC copies the MTP settings to the registers. With a read action of the Ringo, the settings are copied to the GUI on your screen.

## 6 I<sup>2</sup>C communication

Besides the normal TEA2016 ICs, NXP Semiconductors provides special IC versions for product development. The difference is that the development IC samples provide a second I<sup>2</sup>C interface for easy modification of settings while the IC is operating: changing operation on the fly.



### 6.1 Development IC samples: SDA and SCL on spacer pins

Connections to the second  $I^2C$  interface of the IC are provided on the pins that are normally not connected, high-voltage spacer pins 7 and 12.



The basic I<sup>2</sup>C interface functions on the combined function pins of the IC are also available on development samples. However, they are disabled because only 1 channel

UM11219

**UM11219** 

can be functional. The configuration is set at NXP Semiconductors IC production. It cannot be modified by the user.

### 6.2 Production IC samples: SDA and SCL on combined pins

The basic I<sup>2</sup>C interface in the IC is available on the combined pins SNSCURPFC (SCL) and SNSCAP (SDA). To program the IC, the IC must be put in the disabled condition pulling SNSBOOST to GND. During programming, SUPIC must supply the IC.

Programming can be done on a separate IC (put in an IC socket) or when the IC is mounted on the power supply PCB.

When programming is done while the IC is mounted on the power supply board, the capacitive and resistive loads on the SDA and SCL lines become much higher. The much higher capacitive and resistive loads endanger communication because rise times and fall times of the communication pulses become much slower and distorted. Depending on the application component values, the driver capability of the I<sup>2</sup>C interface must be modified to ensure reliable programming.



Figure 26. Two TEA2016 programming setups: on-the-fly and standalone

UM11219

## 6.3 Graphical user interface (GUI) and USB-I<sup>2</sup>C interface

During power supply development, the communication with the IC is done by the Ringo software with GUI on a computer and a USB-I<sup>2</sup>C hardware interface. The TEA2016 GUI provides the correct protocol and offers several options and tools to work with the IC settings.

This document and the USB-I<sup>2</sup>C interface user manual show how to work with it.



### 7 Setting modification using an external GATELS resistor value

The TEA2016 offers a possibility to modify a group of settings with an external resistor value on GATELS without MTP programming.

A resistor measurement function in the IC measures the value of the resistor to GND on GATELS. Applying a certain resistor value gives the option to select one of the 4 preselected "menus" each consisting of a group of basic settings related to protections (see Figure 28). It mainly offers a choice between safe restart or latched follow-up character.

Four sets of 8 parameter settings can be chosen. When these sets are programmed, they can be used without reprogramming. Menu R1, Menu R2, Menu R3, and Menu R4 represent the four sets. Figure 28 shows an example of programmed menus.

The 32 fields can be modified independently. However create 4 useful menus that can cover a small variation between applications.

Typically, changing settings with resistor values can be a solution for using the same power supply, changing it from "safe restart" to "latched" using the GATELS resistor value. It is also possible to use different protection power levels (OCP and OPP) in the menus.

Other parameter settings do not change with the resistor value.

		-								
$\bigcirc$	TEA201	6								
Pro	0 10 30				Op	p1	Opp2	155		
9	BM LP			HP						Pout (%
	Configuration Miscellaneous	Info sheet					Reset		Pro	tection stat
9	Configuration				Configuration					
		R1 <= 100k			R2 = 120k		R3 = 150k		R4 >= 180k	
	OTP	safe restart	-	0	safe restart	-	latched	•	latched	•
100000000000000000000000000000000000000	Over Current Protection Filter LLC	5	•	0	20	•	5	•	20	•
	OPP Time 1 to Protect	50ms	-	0	100ms	•	50ms	•	100ms	•
	OPP	safe restart	•	0	safe restart	-	latched	-	latched	•
( 55 M	OVP	safe restart	•	0	safe restart	•	latched	•	latched	•
	LLC OCP	safe restart	-	0	safe restart	-	latched	•	latched	•
	Safe Restart Timer	1s	-	0	2s	-	1s	•	1s	•
100	PFC OVP-drainPFC	safe restart	-	0	safe restart	-	latched	•	latched	•
<b>(</b>										
	# FT232H (SN: FT1WRIVA). UM232H	4			NXP confidentia	1			•••	

UM11219 User manual

## Ringo TEA2016 development software with GUI

## 8 References

[1]	TEA2016AAT data sheet	<ul> <li>Digital controller for high-efficiency resonant power supply; 2019, NXP Semiconductors</li> </ul>
[2]	UM11235 user manual	<ul> <li>TEA2016DB1514 USB I<sup>2</sup>C interface board; 2019, NXP Semiconductors</li> </ul>
[3]	UM11234 user manual	<ul> <li>TEA2016 240 W prototype demo board;</li> <li>2019, NXP Semiconductors</li> </ul>
[4]	AN12330 application note	<ul> <li>TEA2016AAT digital controller for high-efficiency PFC and resonant power supplies; 2019, NXP Semiconductors</li> </ul>

#### Ringo TEA2016 development software with GUI

## 9 Legal information

### 9.1 Definitions

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### **NXP Semiconductors**

# UM11219

Ringo TEA2016 development software with GUI

### Contents

1	Introduction	3
1.1	Software license agreement	3
1.2	Different appearance	3
1.3	Fixed window pixel size GUI window	3
1.4	64-bit and 32-bit versions	3
2	Setup and functions of Ringo	4
2.1	Chapters and tabs	4
2.2	Selecting a parameter value	5
2.3	Adding modification restrictions	5
3	Information	9
3.1	Protection registers and LEDs	9
3.2	Info buttons	10
3.3	Mode transitions and protection levels on a	
	power scale	. 11
3.4	Warnings	11
3.5	Search function	12
4	Writing and reading settings (IO)	13
4.1	W and R button	13
4.2	Read lock and write lock	13
4.3	Reset to factory defaults	14
4.4	Info sheet	14
4.5	Connection	15
4.6	Connection quality	15
5	TEA2016 MTP and registers	17
5.1	MTP memory and registers	17
5.1.1	IC operation	17
5.1.2	Default settings	17
5.1.3	Saving and loading setting by .mif file	. 18
5.1.4	List of settings	19
5.1.5	Double check changed settings	19
6	I2C communication	20
6.1	Development IC samples: SDA and SCL on	
	spacer pins	20
6.2	Production IC samples: SDA and SCL on	
	combined pins	. 21
6.3	Graphical user interface (GUI) and USB-I2C	
	interface	22
7	Setting modification using an external	
	GATELS resistor value	23
8	References	24
9	Legal information	25

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